

Patent claims

1. An integrated circuit arrangement (1) comprising a
5 nonplanar substrate (2) on which an integrated circuit
is formed on at least one side,
characterized in that
that side (3) of the substrate (2) which has the
integrated circuit is arranged on a carrier (4) and the
10 carrier (4) is produced from a chemically resistant
material.

2. The integrated circuit arrangement (1) as claimed
in claim 1,
15 characterized in that
the chemically resistant material of the carrier (4) is
formed from ceramic.

3. The integrated circuit arrangement (1) as claimed
20 in claim 1 or 2,
characterized in that
the carrier (4) has a planar surface on a side (6)
which is remote from the integrated circuit.

- 25 4. The integrated circuit arrangement (1) as claimed
in one of claims 1 to 3,
characterized in that
the substrate (2) is connected to the carrier (4) over
the entire area.

- 30 5. The integrated circuit arrangement (1) as claimed
in one of claims 1 to 4,
characterized in that
the carrier (4) has a cavity (5) in which the substrate
35 (2) is completely held.